

What is claimed is:

[Claim 1] 1. A heat sink, comprising:

a hollow chassis, comprising a contact face at a bottom portion thereof for attaching to an electronic component and a heat dissipating face at a top portion thereof, and a plurality of circularly arranged fins extending from an inner sidewall of said hollow chassis towards a center of said hollow chassis so that gaps between said fins gradually decrease from said inner sidewall of said hollow chassis towards said center of said hollow chassis; and
at least a heat pipe, positioned between said contact face and said heat dissipating face, wherein at least a fan is positioned at a side of said hollow chassis for generating air to increase an amount of air blowing through wider gaps between said fins to increase a speed of heat dissipation.

[Claim 2] 2. The heat sink according to claim 1, wherein said heat pipe comprises a base, and a heat conducting portion and a heat dissipating portion away from said heat conducting portion respectively extending from said base, and wherein said heat conducting portion and said heat dissipating portion are respectively attached in said contact face and said heat dissipating face of said hollow chassis.

[Claim 3] 3. The heat sink according to claim 1, wherein said heat sink comprises one or more heat pipes.

[Claim 4] 4. The heat sink according to claim 1, wherein said contact face and said heat dissipating face of said hollow chassis have inlaying groove respectively for inlaying said heat conducting portion and said heat dissipating portion of said heat pipe.

[Claim 5] 5. The heat sink according to claim 1, wherein said hollow chassis comprises a fan at two sides thereof respectively, and wherein said fan at one side is adapted for sucking air from outside and said fan at the other side is adapted for blowing air to outside.